IN THE SPECIFICATION:

Page 1, delete the paragraph [0002] and replace it with the following new paragraph:

2. Description of the Related Art

[0002] A lithographic apparatus is a machine that applies a desired pattern onto a target portion of a substrate. Lithographic apparatus can be used, for example, in the manufacture of integrated circuits (ICs). In that circumstance, a patterning device, such as a mask, may be used to generate a circuit pattern corresponding to an individual layer of the IC, and this pattern can be imaged onto a target portion (e.g. including part of one, or several, dies) on a substrate (e.g. a silicon wafer) that has a layer of radiation-sensitive material (resist). In general, a single substrate will contain a network of adjacent target portions that are successively exposed. Known lithographic apparatus include so-called steppers, in which each target portion is irradiated by exposing an entire pattern onto the target portion at once, and so-called scanners, in which each target portion is irradiated by scanning the pattern through the ~~projection~~ beam in a given direction (the "scanning" direction) while synchronously scanning the substrate parallel or anti-parallel to this direction.

Page 4, delete the paragraph [0015] and replace it with the following new paragraph:

[0015] According to a further aspect of the present invention, there is provided a device manufacturing method including ~~providing a substrate;~~ providing radiation at a first wavelength range and at a second wavelength range, the second wavelength range being different from the first wavelength range; patterning the radiation in its cross section; and projecting the patterned radiation onto a target portion of the substrate. The first and second wavelength range radiation may be provided simultaneously, or in different time windows.

Page 5, delete the paragraph [0021] and replace it with the following new paragraph:

[0021] The support supports, e.g., ~~bares~~ bears the weight of, the patterning device. It holds the patterning device in a way depending on the orientation of the patterning device, the design of the lithographic apparatus, and other conditions, such as for example whether or not the patterning device is held in a vacuum environment. The support can use mechanical clamping, vacuum, or other clamping techniques, for example electrostatic clamping under

PAGE 7/18 * RCVD AT 10/19/2005 3:36:00 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/41 * DNIS:2738300 * CSID:703 905 2500 * DURATION (mm-ss):04-24

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vacuum conditions. The support may be a frame or a table, for example, which may be fixed or movable as required and which may ensure that the patterning device is at a desired position, for example with respect to the projection system. Any use of the terms "reticle" or "mask" herein may be considered synonymous with the more general term "patterning device".

Page 8, delete the paragraph [0036] and replace it with the following new paragraph:

[0036] The depicted apparatus can be used in the following preferred modes:

1. In step mode, the mask table MT and the substrate table WT are kept essentially stationary, while an entire pattern imparted to the ~~projection~~ beam is projected onto a target portion at once (i.e. a single static exposure). The substrate table WT is then shifted in the X and/or Y direction so that a different target portion can be exposed. In step mode, the maximum size of the exposure field limits the size of the target portion imaged in a single static exposure.

2. In scan mode, the mask table MT and the substrate table WT are scanned synchronously while a pattern imparted to the beam is projected onto a target portion (i.e. a single dynamic exposure). The velocity and direction of the substrate table WT relative to the mask table MT is determined by the (de-)magnification and image reversal characteristics of the projection system PL. In scan mode, the maximum size of the exposure field limits the width (in the non-scanning direction) of the target portion in a single dynamic exposure, whereas the length of the scanning motion determines the height (in the scanning direction) of the target portion.

3. In another mode, the mask table MT is kept essentially stationary holding a programmable patterning device, and the substrate table WT is moved or scanned while a pattern imparted to the beam is projected onto a target portion. In this mode, generally a pulsed radiation source is employed and the programmable patterning device is updated as required after each movement of the substrate table WT or in between successive radiation pulses during a scan. This mode of operation can be readily applied to maskless lithography that utilizes programmable patterning device, such as a programmable mirror array of a type as referred to above.

PAGE 8/18 * RCVD AT 10/19/2005 3:36:00 PM [Eastern Daylight Time] * SVR:USPTO-EFXRF-6/41 * DNIS:2738300 * CSID:703 905 2500 * DURATION (mm-ss):04-24

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